**Features**
- Single Biasing Voltage (Self Biased)
- Frequency: 2-26GHz
- Gain: 15dB
- Noise Figure: 1.5~3.6dB
- Input /Output Return Loss: >17dB/ >11dB
- P1dB: 10.3~15dBm
- IP3: 26dBm
- Power Supply: +5 V@60 mA
- Die Size: 3.12 x 1.38 x 0.1 mm

**Typical Applications**
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

**Electrical Specifications**
*TA = +25°C, Vd = +5V*

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Low Noise Amplifier - MMIC 2-26GHz

- **Small Signal Response (25°C)**
  - frequency vs. small signal response (dB)
  - lines for different temperatures

- **Gain vs. Temperature**
  - frequency vs. gain (dB)
  - lines for different temperatures

- **Noise Figure vs. Temperature**
  - frequency vs. noise figure (dB)
  - lines for different temperatures

- **P1dB vs. Temperature**
  - frequency vs. P1dB (dBm)
  - lines for different temperatures

- **Psat vs. Temperature**
  - frequency vs. Psat (dBm)
  - lines for different temperatures

- **OIP3 (25°C)**
  - frequency vs. OIP3 (dBm)
  - line for different temperatures
Outline Drawing:
All Dimensions in μm

Assembly Drawing

Notes:
1. Die thickness: 100um
2. Typical bond pad is 100*100 μm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads
7. Internal DC Block at both input and output.
8. Input/Output use two 25um gold wire, length less than 250um is recommended.

Maximum Ratings:
1. Control voltage: +9V
2. Input power: +23dBm
3. Operating temperature: -55°C to +125°C
4. Storage temperature: -65°C to +150°C